

On page 1, please delete the first complete paragraph and insert the following replacement paragraph:

A2 The present invention relates generally to a process for producing IC (integrated circuit) cards. More particularly, the present invention relates to a process for producing cards, which can avoid exposure, on the card surface, of unevennesses of components such as IC chips, capacitors and antenna coils mounted or formed on a mount substrate.

A3 **On page 4, please amend the section heading "DISCLOSURE OF THE INVENTION" to read as follows:**

SUMMARY OF THE INVENTION

A4 **On page 6, please amend the section heading "BRIEF DESCRIPTION OF THE DRAWING" to read as follows:**

BRIEF DESCRIPTION OF THE DRAWINGS

A5 **On page 7, please amend the section heading "BEST MODE FOR CARRYING OUT THE INVENTION" to read as follows:**

DETAILED DESCRIPTION OF THE INVENTION

A6 **On page 9, please delete the second complete paragraph and insert the following replacement paragraph:**

Further, an adhesive 28, 30 in fluid condition is fed over respective surfaces 20A, 22A of the sheet members 20, 22 delivered from the sheet member supply rolls 16, 18 through adhesive supply means 32, 35 such as die coaters or T-dies.

A7 **On page 9, please delete the third complete paragraph and insert the following replacement paragraph:**

After the application of the adhesive 28, 30 in fluid condition over the respective surfaces 20A, 22A of the sheet members 20, 22, the sheet members 20, 22 are

guided by means of the pair of guide rolls 24, 26 so that the mount substrate 12 is interposed between the sheet members 20, 22 and so that the spaces defined by both surface sides of the mount substrate 12 and the sheet members 20, 22 are filled with the adhesive 28, 30.

Page 17, delete the section heading "EFFECT OF THE INVENTION".